MAZLxxxH Series

Silicon planar type

For surge absorption circuit

Features

- Four elements anode-common type
- Power dissipation P_D : 200 mW

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Power dissipation *	P_{D}	200	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

Note) *: $P_D = 200 \text{ mW}$ achieved with a printed circuit board.



Internal Connection



Common Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol		Conditions	Min	Тур	Max	Unit	
Zener voltage*	VZ	IZ	Specified value					V
Zener rise operating resistance	R _{ZK}	IZ	Specified value	er to the list of the			Ω	
Zener operating resistance	R _Z	IZ	Specified value	within part numbers				Ω
Reverse current	I _R	V _R	Specified value					μΑ

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Electrostatic breakdown voltage: $\pm 10 \text{ kV}$

Test method: IEC1000-4-2 (C = 150 pF, R = 330 Ω , Contact discharge: 10 times)

3. *: The temperature must be controlled 25°C for $V_{\rm Z}$ mesurement.

 V_Z value measured at other temperature must be adjusted to $V_Z\,(25^\circ C)$

 V_Z guaranted 20 ms after current flow.

MAZLxxxH Series

Panasonic

	Zener voltage				Reverse current		Zener operating	Zener rise operating	
Part number	$V_{Z}(V)$				I _R (mA)		$R_{Z}(\Omega)$	$R_{ZK}(\Omega)$	Marking symbol
				Ι _Ζ		V _R	$I_z = 5 \text{ mA}$	$I_{z} = 0.5 \text{ mA}$	
	Min	Nom	Max	(mA)	Max	(V)	Max	Max	
MAZL068H	6.4	6.8	7.2	5	0.1	4	30	60	6.8Z
MAZL082H	7.7	8.2	8.7	5	0.1	5	30	60	8.2Z
MAZL120H	11.4	12.0	12.7	5	0.05	9	30	80	12Z

	Electrical	characteristics	within	part numbers	$T_{\circ} = 25^{\circ}C \pm 3^{\circ}C$
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